

# DRAFT

## Semiconductor and Related Devices Industry Preliminary 2006 Survey Results

Type of FG	CVD Cleaning (Kg)	Etching (Kg)	Other Processes (Kg)	Total FG Usage (Kg)
C <sub>2</sub> F <sub>6</sub>	28,698	7,266	42	36,006
C <sub>3</sub> F <sub>8</sub>	7,502	1,275	0	8,777
CF <sub>4</sub>	3,339	11,235	257	14,831
CHF <sub>3</sub>	408	3,760	171	4,339
C <sub>4</sub> F <sub>8</sub>	4,401	901	61	5,363
C <sub>4</sub> F <sub>8</sub> O	129	0	138	267
C <sub>4</sub> F <sub>6</sub>	0	546	0	546
NF <sub>3</sub>	16,205	3,525	141	19,871
SF <sub>6</sub>	386	8,899	964	10,249
Other FGs:	18	32	679	729
<b>Total FG Usage</b>	<b>61,086</b>	<b>37,439</b>	<b>2,453</b>	<b>100,978</b>

CVD Cleaning	Etching	Other Processes
60	37	3

MMTCO <sub>2</sub> E (excludes NF <sub>3</sub> )	MMTCO <sub>2</sub> E (includes NF <sub>3</sub> )
0.26 <sup>2</sup>	0.27 <sup>3</sup>

Footnotes:

1. Preliminary emissions estimates calculated using Tier 2b formula from the "2006 Intergovernmental Panel on Climate Change (IPCC) Guidelines for National Greenhouse Gas Inventories."
2. Preliminary emissions estimate based on the IPCC 1996 Global Warming Potential (GWP) values, and excludes NF<sub>3</sub>.
3. Preliminary emissions estimate based on the IPCC 1996 GWP values for 6 FGs, and the IPCC 2006 GWP value for NF<sub>3</sub>.